


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16070	
1.3 Title of PCN	AMKOR ATJ (Japan) additional source for STM32H562x, STM32H563x and STM32H573x products in LQFP14x14 100L and LQFP20x20 144L packages.	
1.4 Product Category	STM32H562x, STM32H563x and STM32H573x.	
1.5 Issue date	2026-06-16	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	AMKOR ATJ (Japan)

4. Description of change

	Old	New
4.1 Description	STM32H562x, STM32H563x and STM32H573x assembly sites: - ASE Kaohsiung (Taiwan)	STM32H562x, STM32H563x and STM32H573x assembly sites: - ASE Kaohsiung (Taiwan) - current assembly - AMKOR (ATJ3) Japan - additional assembly site
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form: change visible on the Marking composition.	

5. Reason / motivation for change

5.1 Motivation	Second source introduction
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking with PP code changing - from AA : ASE KaoHsiung (Taiwan) - to 6Z: Amkor ATJ (Japan) Please refer to PCN 16070_Additional information.pdf document for further details.
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7. Timing / schedule

7.1 Date of qualification results	2026-09-30
7.2 Intended start of delivery	2026-10-05
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16070 RER2517 ATJ3 LQFP14x14 to 20X20 CuPd wire STM32- reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-06-16

9. Attachments (additional documentations)

16070 Public product.pdf
16070 RER2517 ATJ3 LQFP14x14 to 20X20 CuPd wire STM32- reliability plan.pdf
16070 _Additional information.pdf

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H562VGT6	
	STM32H562VIT6	
	STM32H562ZGT6	
	STM32H562ZIT6	
	STM32H563VGT6	
	STM32H563VIT6	
	STM32H563ZGT6	
	STM32H563ZIT6	
	STM32H573VIT6	
	STM32H573ZIT6	

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